Supplementary Materials

Article

Thermal Isolation of a Clean Alloy from Waste Slag and Polymeric Residue of Electronic Waste

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Table S1. The name and molecular structures of the compounds recognized at the mass spectrum illustrated in *Error! Reference source not found.*.

No.	Compound	Molecular structure	No.	Compound	Molecular structure
1	1-Bromo- butane	H H Br	2	Styrene	H C C E
3	Phenol		4	2-Methyl- 3,3,5- trimethyleyclo hexyl-2 propenoic acid	
5	2-Boromo- phenol		6	cis-p-Mentha- 2,8-dien-1-ol	
7	2,3-Dihydro- 2-methyl- benzofuran	H C C C U	8	2-Allylphenol	

